



DuPont™ Posistrip® EKC800™ Series

Photoresist Removers

For Positive Photoresist Removal

Product Description

DuPont™ Posistrip® photoresist removers are organic blends specifically formulated to remove positive photoresist from substrate surfaces used in the microelectronics industry.

Formulated to meet a wide range of process requirements, Posistrip® products vary from mildly aggressive non-alkaline chemistries for removal of photoresist from sensitive metal layers or substrates like GaAs, to very aggressive alkaline chemistries for removal of extremely hardened photoresist. These water-rinsable formulations allow the user to complete the photoresist removal process with less chemistry and lower cost of ownership (CoO). These products are low in metal ions, non-corrosive to sensitive metals and contain no phenol or chlorinated solvents. Posistrip® products are compatible with automatic equipment allowing for easy conversion from manual wet station environments.

DuPont™ Posistrip® EKC800™ Series photoresist removers include:

Posistrip® EKC800™

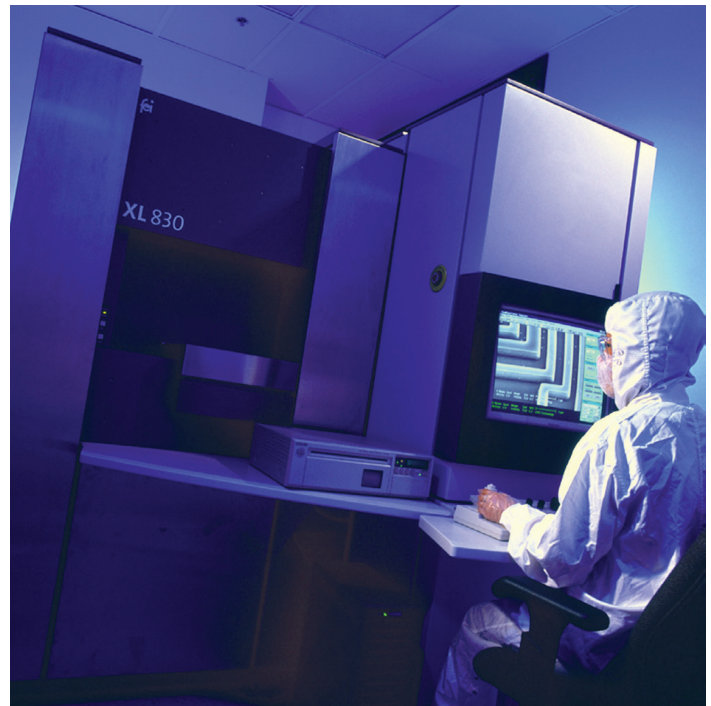
Designed to remove positive photoresist that has experienced standard processing with normal thermal history.

Posistrip® EKC830™

Designed to effectively remove positive photoresist resulting from harsh prior processing that is difficult to remove.

Posistrip® EKC865™

Specifically formulated to prevent attack of sensitive metals. Removes positive photoresist with normal thermal history.





ekctech.dupont.com

For more information on DuPont™ Posistrip® EKC800™ or other DuPont products, please visit our website.

The information provided in this data sheet corresponds to our knowledge on the subject at the date of its publication. It may be subject to revision as new knowledge and experience becomes available. This information is not intended to substitute for any testing you may need to conduct to determine for yourself the suitability of our products for your particular purposes. Since we cannot anticipate all variations in end-use and disposal conditions, DuPont makes no warranties and assumes no liability in connection with any use of this information. It is intended for use by persons having technical skill, at their own discretion and risk. Nothing in this publication is to be considered as a license to operate under or a recommendation to infringe any patent right.

CAUTION: Do not use in medical applications involving permanent implantation in the human body. For other medical applications, see "DuPont Medical Caution Statement," H-50102-5 and "DuPont Policy Regarding Medical Applications" H-50103-5.

DuPont™, the DuPont Oval Logo, and all products, unless otherwise noted, denoted with ™, SM or ® are trademarks, service marks or registered trademarks of affiliates of DuPont de Nemours, Inc. © 2019 DuPont de Nemours, Inc. All rights reserved.

K-10773-4 (06/19)